



N-Ch MOSFET

#### **General Description**

The WSR25N20G is the highest performance trench N-Ch MOSFET with extreme high cell density,which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSR25N20G meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline

Absolute Maximum Ratings

• Green Device Available

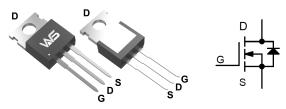
### **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
200V	57mΩ	36A

#### Applications

- High Frequency Point-of-Load Synchronous
  Buck Converter
- Networking DC-DC Power System
- Load Switch

#### **TO-220F Pin Configuration**



#### Symbol **Parameter** Rating Units 200 v **Drain-Source Voltage** $V_{DS}$ V Gate-Source Voltage $\pm 20$ $V_{\text{GS}}$ Continuous Drain Current, V<sub>GS</sub> @ 10V<sup>1</sup> 36 А I<sub>D</sub>@T<sub>C</sub>=25℃ Continuous Drain Current, V<sub>GS</sub> @ 10V<sup>1</sup> 25 I<sub>D</sub>@T<sub>C</sub>=100℃ А Pulsed Drain Current<sup>2</sup> 150 А $I_{DM}$ Single Pulse Avalanche Energy<sup>3</sup> EAS 273 mJ PD 90 W Total Power Dissipation<sup>3</sup> °C T<sub>STG</sub> Storage Temperature Range -55 to 175 °C ΤJ **Operating Junction Temperature Range** -55 to 175

### Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R <sub>eJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>		62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		0.83	°C/W



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#### Electrical Characteristics (T<sub>J</sub>=25<sup>1</sup>C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	200			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$ , I_D=1mA		0.098		V/℃
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =15A		57	68	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		3.0	3.8	5.0	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS, ID-2300A		-4.57		mV/℃
	Drain Source Leekage Current	$V_{DS}$ =160V , $V_{GS}$ =0V , $T_J$ =25 $^\circ C$			1	- uA
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =160V , $V_{GS}$ =0V , $T_J$ =55 $^\circ\!\!\!\mathrm{C}$			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm25V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =15A		32		S
Qg	Total Gate Charge (10V)			53		
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS}$ =100V , $V_{GS}$ =10V , $I_{D}$ =15A		11		nC
Q <sub>gd</sub>	Gate-Drain Charge			15		]
T <sub>d(on)</sub>	Turn-On Delay Time			30		
Tr	Rise Time	$V_{DD}$ =30V , $V_{GS}$ =10V ,		20		
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>G</sub> =6Ω, I <sub>D</sub> =15A, R∟=30Ω		21		ns
T <sub>f</sub>	Fall Time			31		
C <sub>iss</sub>	Input Capacitance			2445		
Coss	Output Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , f=1MHz		129		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			24		

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>				36	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	$V_G = V_D = 0V$ , Force Current			150	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =12A , TJ=25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time			48		nS
Qrr	Reverse Recovery Charge	IF=12A , dI/dt=100A/µs , Tյ=25℃		78		nC

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition: Tj=25 $^\circ\!\mathrm{C},V_{DD}$ =50V,V\_G=10V,L=0.5mH,Rg=25 $\Omega$



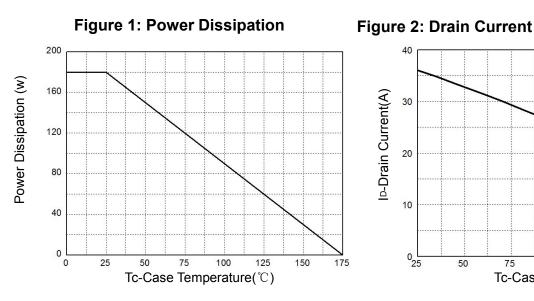
**WSR25N20G** 

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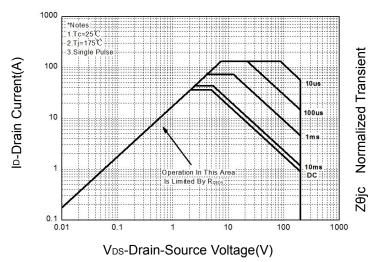
150

175

# **Typical Operating Characteristics(Cont.)**







**Figure 4: Thermal Transient Impedance** 

75

100

Tc-Case Temperature(°C)

125

40

30

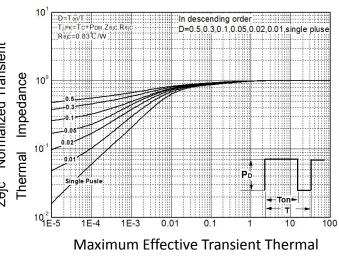
20

10

0 L

50

D-Drain Current(A)



Impedance, Junction-to-Case



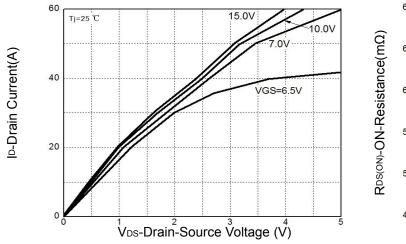
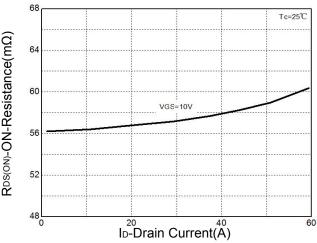


Figure 6: Drain-Source On Resistance





# Typical Operating Characteristics(Cont.)

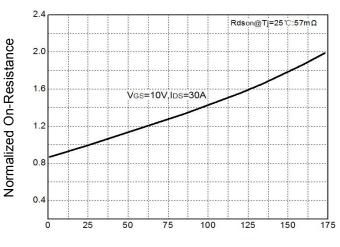
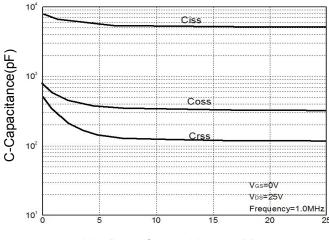


Figure 7: On-Resistance vs. Temperature

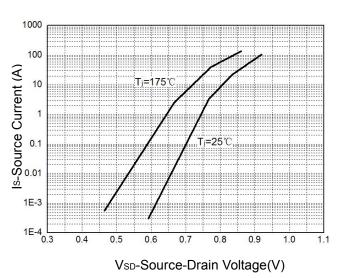
Tj-Junction Temperature (℃)

### **Figure 9: Capacitance Characteristics**

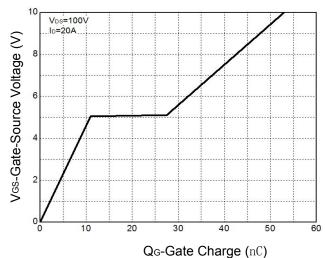


VDS-Drain-Source Voltage (V)

# Figure 8: Source-Drain Diode Forward



### Figure 10: Gate Charge Characteristics

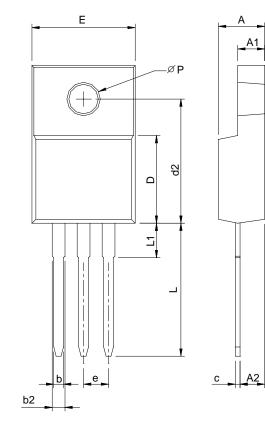


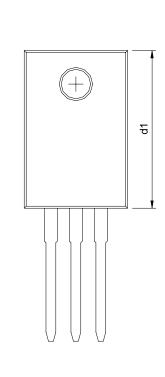


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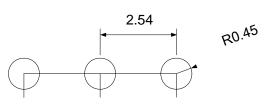
## **TO-220F** Package Information





Ş	TO-220F				
S≻-Mano_	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	4.20	4.80	0.165	0.189	
A1	2.34	3.20	0.092	0.126	
A2	2.10	2.90	0.083	0.114	
b	0.50	0.90	0.020	0.035	
b2	0.91	1.90	0.035	0.075	
с	0.30	0.80	0.012	0.031	
D	8.10	9.40	0.319	0.370	
d1	14.50	16.50	0.571	0.650	
d2	12.10	12.90	0.476	0.508	
Е	9.70	10.70	0.382	0.421	
е	2.54 BSC		0.10	0 BSC	
L	13.00	14.50	0.512	0.570	
L1	1.60	4.00	0.063	0.157	
Р	3.00	3.60	0.118	0.142	

**RECOMMENDED LAND PATTERN** 



UNIT: mm



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